Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

What is claimed is:

1. [currently amended] A heat sink assembly comprising:

a heat sink; ~~and~~

a bracket for mounting said heat sink to a component located on a circuit board, and

~~wherein said bracket cooperates with said heat sink~~a retaining clip assembly to couple the heat sink to the bracket and allow rotation between the heat sink and the bracket thereby allowing said heat sink to be ~~set in~~rotated to an installation orientation ~~of a plurality of orientations~~ relative to said bracket prior to mounting said heat sink against said component.

2. [currently amended] The heat sink assembly of claim 1, wherein said heat sink further comprises a pedestal and said bracket further defines an opening, said retaining clip assembly co-operating with a groove in said pedestal ~~cooperating with~~and said opening ~~allowing~~to allow said heat sink to be ~~set in~~rotated to said installation orientation.

3. [original] The heat sink assembly of claim 2 wherein said bracket is mountable about said component to said circuit board.

4. [currently amended] The heat sink assembly of claim ~~3 further comprising a~~2 wherein said retaining clip assembly comprises a penannular retaining ~~ring~~clip cooperable with a groove in said pedestal and said bracket to retain said heat sink within said opening when said bracket is mounted to said circuit board.

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5. [original] The heat sink assembly of claim 4 further comprising a housing enclosing said heat sink therein, said housing having at least one open end.

6. [original] The heat sink assembly of claim 5, wherein said housing is rotatable about said heat sink.

7. [original] The heat sink assembly of claim 3, wherein said bracket further comprises a bevel directing airflow towards said heat sink.

8. [original] The heat sink assembly of claim 7 wherein said bracket comprises stamped metal.

9. [original] The heat sink assembly of claim 8 wherein said bracket is mountable about said component to said circuit board by a fastener securing a leaf on said bracket to said circuit board.

10. [original] The heat sink assembly of claim 9 wherein said leaf is initially biased away from said circuit board prior to being secured to said circuit board by said fastener.

11. [original] The heat sink assembly of claim 10, wherein a feature on said bracket cooperates with a feature on said pedestal to provide said installation orientation for said heat sink.

12. [original] The heat sink assembly of claim 11, wherein said feature on said bracket is a key and said feature on said pedestal is a rebate.

13. [original] The heat sink assembly of claim 11, wherein said feature on said pedestal is a key and said feature on said bracket is a rebate.

14. [original] The heat sink assembly of claim 10, a feature on said bracket cooperates with a feature on said pedestal to inhibit rotation of said heat sink about said bracket in one direction.

15. [original] The heat sink assembly of claim 14, wherein said feature on said pedestal is a key and said feature on said bracket is a raised flange.

16. [original] The heat sink assembly of claim 10 wherein said bracket comprises formed wire.

17. [currently amended] A heat sink assembly comprising:

a heat sink;

a bracket for mounting said heat sink to a structure associated with a circuit board; ~~and~~

a vane connected to said apparatus for directing air flow; and

a retaining clip assembly to retain said heat sink to said bracket,

wherein said ~~bracket~~retaining clip assembly permits said heat sink to be ~~oriented in one of a plurality of positions~~rotated relative to said bracket prior to mounting said heat sink to said circuit board.

18.[new] A heat sink assembly comprising:

a heat sink;

a housing enclosing said heat sink having at least one open end through which air is permitted to circulate;

a bracket for mounting said heat sink and housing to a component located on a circuit board; and

a retaining clip assembly to couple the heat sink and the housing to the bracket and allow rotation between the heat sink, the housing and the bracket thereby allowing

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said heat sink and said housing to be rotated to an installation orientation relative to said bracket prior to mounting said heat sink assembly against said component.

19. [new] The heat sink assembly of claim 18, wherein said heat sink further comprises a pedestal and said bracket further defines an opening, said retaining assembly cooperating with said pedestal and said opening to allow said heat sink to be rotated to said installation orientation.

20. [new] The heat sink assembly of claim 18 wherein said retaining clip assembly comprises a penannular retaining ring cooperable with said pedestal and said bracket to retain said heat sink within said opening when said bracket is mounted to said circuit board.

21. [new] The heat sink assembly of claim 18 further including a vane to direct air flow over said heat sink.

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